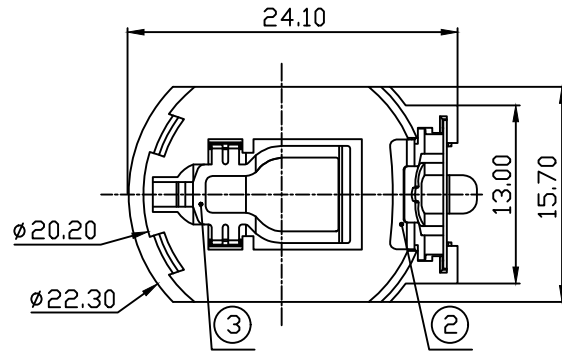
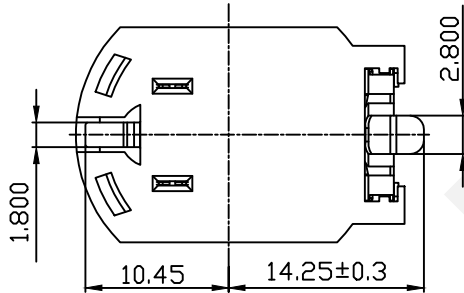


PCB Layout Diagram
Top View



NOTE:

1.MATERIAL:

a.HOUSING:PPA

b.CONTACT:PHOSPHOR BRONZE

(SURFACE PLATING: Au 1u")

2.ELECTRIC:

a.CONTACT RESISTANCE:30 MILLIOHMS MAX

b.INSULATION RESISTANCE:1000 MEA OHMS MIN

c.DIELECTNIC VOLTAGE:500V AC ONE SEC LEVEL

d.OPERATING TEMPERATURE:-25°C~+85°C

3	TERMINAL(-)	1	PHOSPHOR BRONZE,T=0.20mm	Gold Plating And Ni Under-Plating
2	TERMINAL(+)	1	PHOSPHOR BRONZE,T=0.20mm	Gold Plating and Ni Under-Plating
1	HOUSING	1	PPA	BROWN
NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR

RHTECP® NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm

SHEET SIZE: A4

SCALE:---

DRWN BY PAN

CR2032 COIN CELL SMT BATTERY HOLDER

0~3

3~18

18~50

50~120

CHK'D BY FENG

THIRD ANGLE PROJECTION

±0.12

±0.15

±0.3

±0.5

APPR BY ZHAN



RE-BH-CR2032-11